

Global BGA Packaging Solder Ball Supply, Demand and Key Producers, 2024-2030

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Abstracts

The global BGA Packaging Solder Ball market size is expected to reach \$ 236.9 million by 2030, rising at a market growth of 5.9% CAGR during the forecast period (2024-2030).

Market Drivers: Miniaturization of Electronic Devices: The trend toward smaller and more compact electronic devices, such as smartphones, tablets, and wearables, drives the demand for BGA packaging with solder balls. BGA offers a high pin count in a smaller footprint, making it suitable for miniaturized electronics.

Increasing Demand for High-Performance Computing: Growing demand for high-performance computing, data centers, and graphics processing units (GPUs) fuels the adoption of advanced packaging solutions like BGA. Solder balls contribute to the reliability and thermal performance of these high-power components.

Advancements in Semiconductor Technology: Ongoing advancements in semiconductor manufacturing technologies, including finer pitch and higher pin counts, necessitate the development of solder balls with improved materials and manufacturing processes to meet the requirements of next-generation electronic devices.

Rise in Internet of Things (IoT) Devices: The proliferation of IoT devices, which require compact and efficient packaging solutions, boosts the demand for BGA packaging with solder balls. BGA technology supports the integration of sensors and processors in small form factors.

Consumer Electronics Industry Growth: The consumer electronics industry's continual growth, driven by innovations in smartphones, laptops, gaming consoles, and other



electronic gadgets, contributes significantly to the demand for BGA packaging solder balls.

Market Restrictions: Cost and Complexity of Manufacturing: The manufacturing processes involved in producing BGA packaging with solder balls can be complex and may require advanced equipment. The associated costs, including material and manufacturing expenses, could be a limitation for some manufacturers or applications.

Stringent Quality and Compliance Standards: Industries such as aerospace and automotive have stringent quality and compliance standards. Meeting these standards, including requirements for high-reliability solder joints, can be challenging and may act as a restriction for certain applications.

BGA, or Ball Grid Array, packaging is a type of integrated circuit (IC) packaging used in electronics. In a BGA package, solder balls play a crucial role in connecting the integrated circuit to the printed circuit board (PCB).

This report studies the global BGA Packaging Solder Ball production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for BGA Packaging Solder Ball, and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2023 as the base year. This report explores demand trends and competition, as well as details the characteristics of BGA Packaging Solder Ball that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global BGA Packaging Solder Ball total production and demand, 2019-2030, (Million Units)

Global BGA Packaging Solder Ball total production value, 2019-2030, (USD Million)

Global BGA Packaging Solder Ball production by region & country, production, value, CAGR, 2019-2030, (USD Million) & (Million Units)

Global BGA Packaging Solder Ball consumption by region & country, CAGR, 2019-2030 & (Million Units)



U.S. VS China: BGA Packaging Solder Ball domestic production, consumption, key domestic manufacturers and share

Global BGA Packaging Solder Ball production by manufacturer, production, price, value and market share 2019-2024, (USD Million) & (Million Units)

Global BGA Packaging Solder Ball production by Diameter, production, value, CAGR, 2019-2030, (USD Million) & (Million Units)

Global BGA Packaging Solder Ball production by Application production, value, CAGR, 2019-2030, (USD Million) & (Million Units).

This reports profiles key players in the global BGA Packaging Solder Ball market based on the following parameters – company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Senju Metal, Accurus, DS HiMetal, NMC, MKE, PMTC, Indium Corporation, YCTC and Shenmao Technology, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World BGA Packaging Solder Ball market.

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (Million Units) and average price (US\$/K Units) by manufacturer, by Diameter, and by Application. Data is given for the years 2019-2030 by year with 2023 as the base year, 2024 as the estimate year, and 2025-2030 as the forecast year.

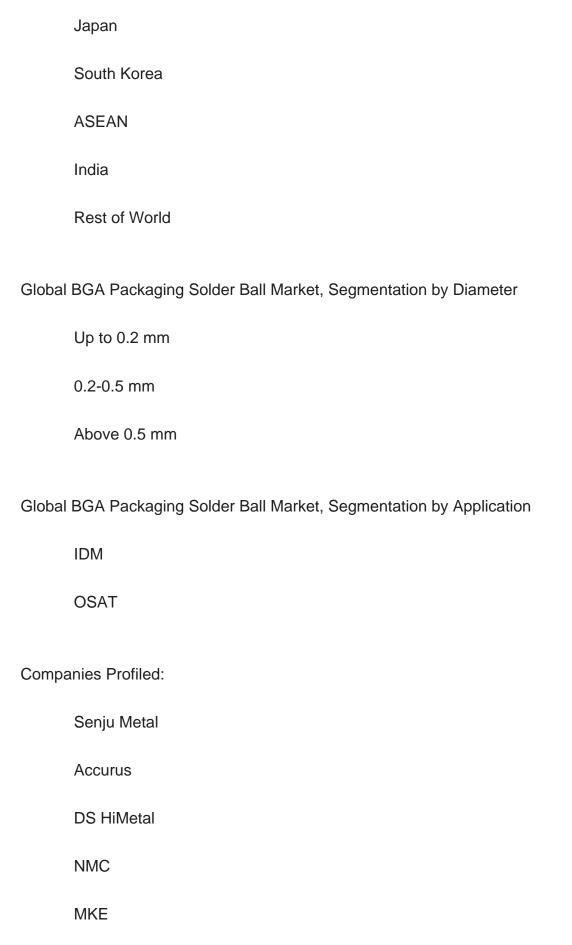
Global BGA Packaging Solder Ball Market, By Region:

United States

China

Europe







market?

PMIC		
Indium Corporation		
YCTC		
Shenmao Technology		
Shanghai hiking solder material		
ey Questions Answered		
How big is the global BGA Packaging Solder Ball market?		
2. What is the demand of the global BGA Packaging Solder Ball market?		

3. What is the year over year growth of the global BGA Packaging Solder Ball market?

4. What is the production and production value of the global BGA Packaging Solder Ball



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